Tool ID: 322
Tool Location: 106

Equipment Information Sheet

AJA-Q2

Manager: Chris Martin 607-254-4855
Backup: Shilling Du 607-254-4907
Backup: Philip Schneider 607-254-4931

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

No significant safety concerns under normal tool operation. Users should exhibit caution when moving to the rear of the tool to adjust off axis gun position.

USAGE RESTRICTIONS
SCHEDULING/SIGN-UP RESTRICTIONS
MATERIALS COMPATIBILITY CATEGORY

Minimum Tool Time: 30 minutes

Tool Category 1E: Silicon Based Materials and Select Dieletrics

Allowed	Not Allowed
Silicon Based Materials only	No Evaporated or Sputtered Films
Si, SiC, SiO_2 substrates	No Metal or Organic Films
All Furnace grown or deposited films	No Glass Substrates
PECVD Films	No III/V Compound Semiconductors
Select ALD dieletrics (SiO_2, SiN, HfO_2, HFN)	No High Vapor pressure materials
Spin on Glass and Spin on Dopants	Organic/Biology Molecules prepared-with or without Salt buffers

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

This tool is restricted to quantum computing research with associated materials. New materials will be evaluated on a case by case basis.

- No photoresist
- No high vapor pressure substrates or films
- Primary materials are Aluminum, Niobium, Tantalum and Titanium

Last Updated: 09/08/2026